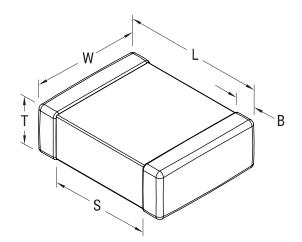


C0603X331FATAC7411

SMD Comm X8G HT150C Flex, Ceramic, 330 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	4.6 mg	
Shelf Life	78 Weeks	
MSL	1	

Time is 1000 Hours

100 GOhms

	Specifications	
3	Capacitance	330 pF
m +/-0.17mm	Measurement Condition	1 MHz 1.0Vrms
nm +/-0.15mm	Tolerance	1%
nm +/-0.15mm	Voltage DC	250 VDC
nm MIN	Dielectric Withstanding Voltage	625 VDC
imm +/-0.15mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
, 330mm, Paper Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
00	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee

Insulation Resistance

 Dimensions

 Chip Size
 0603

 L
 1.6mm +/-0.17mm

 W
 0.8mm +/-0.15mm

 T
 0.8mm +/-0.15mm

 S
 0.4mm MIN

 B
 0.45mm +/-0.15mm

Packaging SpecificationsPackagingT&R, 330mPackaging Quantity15000

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